# 2SB1462

### Silicon PNP epitaxial planar type

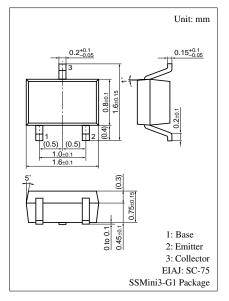
For general amplification Complementary to 2SD2216

#### Features

- $\bullet$  High forward current transfer ratio  $h_{FE}$
- SS-Mini type package, allowing downsizing of the equipment and automatic insertion through the tape packing and the magazine packing

Parameter	Symbol	Rating	Unit				
Collector to base voltage	V <sub>CBO</sub>	-60	V				
Collector to emitter voltage	V <sub>CEO</sub>	-50	V				
Emitter to base voltage	V <sub>EBO</sub>	-7	V				
Peak collector current	I <sub>CP</sub>	-200	mA				
Collector current	I <sub>C</sub>	-100	mA				
Collector power dissipation	P <sub>C</sub>	125	mW				
Junction temperature	Tj	125	°C				
Storage temperature	T <sub>stg</sub>	-55 to +125	°C				

#### Absolute Maximum Ratings $T_a = 25^{\circ}C$



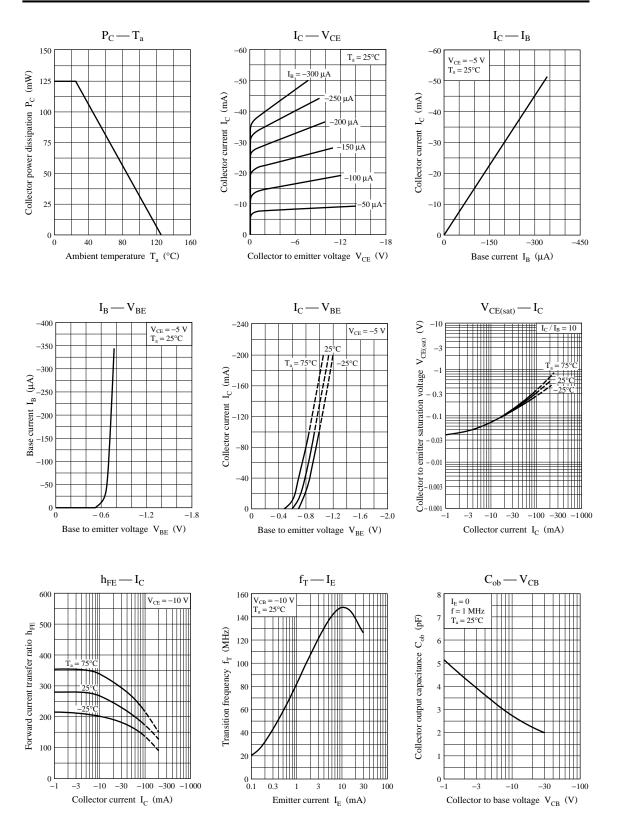
#### Marking symbol: A

#### Electrical Characteristics $T_a = 25^{\circ}C$

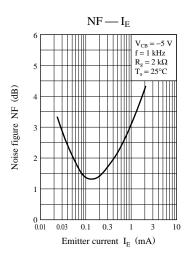
Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Collector cutoff current	I <sub>CBO</sub>	$V_{CB} = -20 \text{ V}, I_E = 0$			- 0.1	μΑ
	I <sub>CEO</sub>	$V_{CE} = -10 \text{ V}, I_B = 0$			-100	
Collector to base voltage	V <sub>CBO</sub>	$I_{C} = -10 \ \mu A, \ I_{E} = 0$	-60			V
Collector to emitter voltage	V <sub>CEO</sub>	$I_{\rm C} = -100 \ \mu A, \ I_{\rm B} = 0$	-50			V
Emitter to base voltage	V <sub>EBO</sub>	$I_E = -10 \ \mu A, \ I_C = 0$	-7			V
Forward current transfer ratio *	h <sub>FE</sub>	$V_{CE} = -10 \text{ V}, I_C = -2 \text{ mA}$	160		460	
Collector to emitter saturation voltage	V <sub>CE(sat)</sub>	$I_{\rm C} = -100 \text{ mA}, I_{\rm B} = -10 \text{ mA}$		- 0.11	- 0.3	v
Transition frequency	f <sub>T</sub>	$V_{CB} = -10 \text{ V}, I_E = 1 \text{ mA}, f = 200 \text{ MHz}$		80		MHz
Collector output capacitance	C <sub>ob</sub>	$V_{CB} = -10 \text{ V}, I_E = 0, f = 1 \text{ MHz}$		2.7		pF

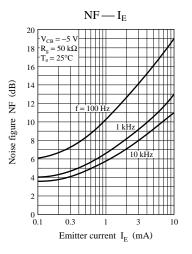
Note) \*: hFE Rank classification

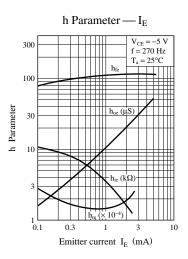
Rank	Q	R	S
h <sub>FE</sub>	160 to 260	210 to 340	290 to 460
Marking symbol	AQ	AR	AS

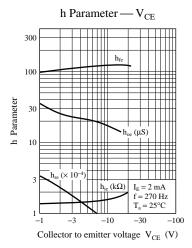


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